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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	18MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LED, POR, PWM, WDT
Number of I/O	26
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 3.6V
Data Converters	A/D 4x8b; D/A 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	28-TSSOP
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/p89lpc933hdh-512

7. Logic symbols

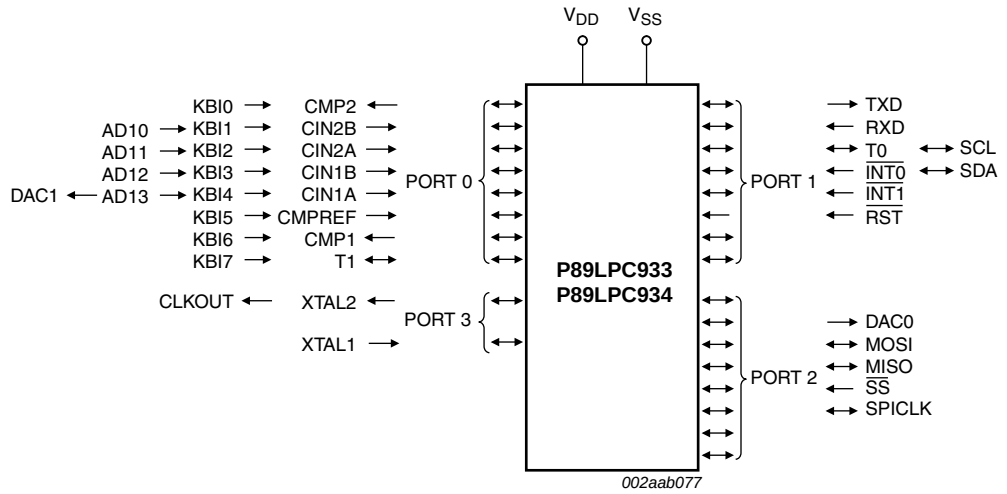

Fig 6. P89LPC933/934 logic symbol

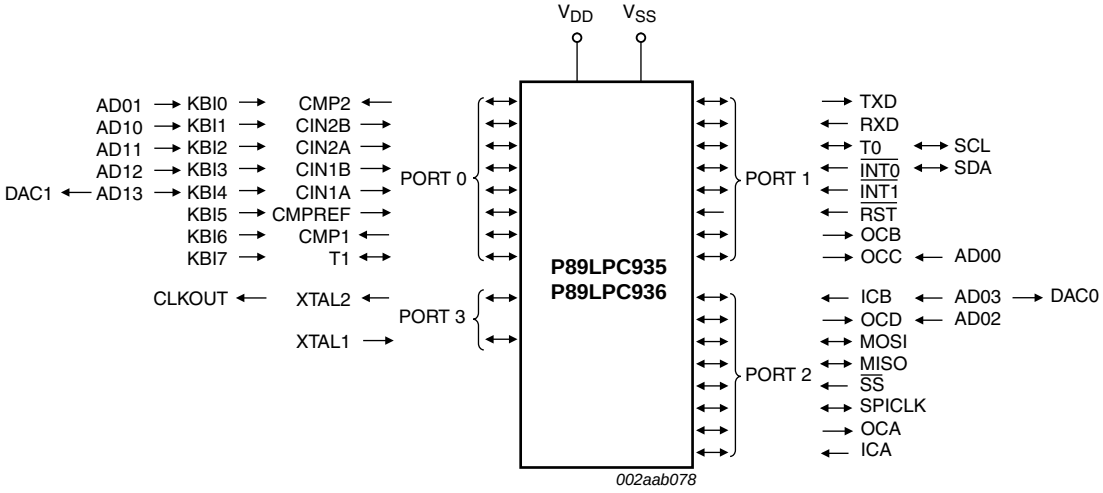

Fig 7. P89LPC935/936 logic symbol

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8. Functional description

Remark: Please refer to the P89LPC933/934/935/936 *User manual* for a more detailed functional description.

8.1 Special function registers

Remark: SFR accesses are restricted in the following ways:

- User must **not** attempt to access any SFR locations not defined.
- Accesses to any defined SFR locations must be strictly for the functions for the SFRs.
- SFR bits labeled '-', logic 0 or logic 1 can **only** be written and read as follows:
  - '-' Unless otherwise specified, **must** be written with logic 0, but can return any value when read (even if it was written with logic 0). It is a reserved bit and may be used in future derivatives.
  - Logic 0 **must** be written with logic 0, and will return a logic 0 when read.
  - Logic 1 **must** be written with logic 1, and will return a logic 1 when read.

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Table 6. Special function registers - P89LPC935/936

** indicates SFRs that are bit addressable.*

Name	Description	SFR addr.	Bit functions and addresses								Reset value	
			MSB							LSB	Hex	Binary
	Bit address		**E7**	**E6**	**E5**	**E4**	**E3**	**E2**	**E1**	**E0**		
ACC*	Accumulator	E0H									00	0000 0000
ADCON0	A/D control register 0	8EH	ENBI0	ENADCI 0	TMM0	EDGE0	ADCI0	ENADC0	ADCS01	ADCS00	00	0000 0000
ADCON1	A/D control register 1	97H	ENBI1	ENADCI 1	TMM1	EDGE1	ADCI1	ENADC1	ADCS11	ADCS10	00	0000 0000
ADINS	A/D input select	A3H	ADI13	ADI12	ADI11	ADI10	ADI03	ADI02	ADI01	ADI00	00	0000 0000
ADMODA	A/D mode register A	C0H	BNDI1	BURST1	SCC1	SCAN1	BNDI0	BURST0	SCC0	SCAN0	00	0000 0000
ADMODB	A/D mode register B	A1H	CLK2	CLK1	CLK0	-	ENDAC1	ENDAC0	BSA1	BSA0	00	000x 0000
AD0BH	A/D_0 boundary high register	BBH									FF	1111 1111
AD0BL	A/D_0 boundary low register	A6H									00	0000 0000
AD0DAT0	A/D_0 data register 0	C5H									00	0000 0000
AD0DAT1	A/D_0 data register 1	C6H									00	0000 0000
AD0DAT2	A/D_0 data register 2	C7H									00	0000 0000
AD0DAT3	A/D_0 data register 3	F4H									00	0000 0000
AD1BH	A/D_1 boundary high register	C4H									FF	1111 1111
AD1BL	A/D_1 boundary low register	BCH									00	0000 0000
AD1DAT0	A/D_1 data register 0	D5H									00	0000 0000
AD1DAT1	A/D_1 data register 1	D6H									00	0000 0000
AD1DAT2	A/D_1 data register 2	D7H									00	0000 0000
AD1DAT3	A/D_1 data register 3	F5H									00	0000 0000
AUXR1	Auxiliary function register	A2H	CLKLP	EBRR	ENT1	ENT0	SRST	0	-	DPS	00	0000 00x0
	Bit address		**F7**	**F6**	**F5**	**F4**	**F3**	**F2**	**F1**	**F0**		
B*	B register	F0H									00	0000 0000
BRGR0[2]	Baud rate generator rate low	BEH									00	0000 0000
BRGR1[2]	Baud rate generator rate high	BFH									00	0000 0000
BRGCON	Baud rate generator control	BDH	-	-	-	-	-	-	SBRGS	BRGEN	00[2]	xxxx xx00
CCCRA	Capture compare A control register	EAH	ICECA2	ICECA1	ICECA0	ICESA	ICNFA	FCOA	OCMA1	OCMA0	00	0000 0000

P89LPC933_934_935_936

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8.2 Enhanced CPU

The P89LPC933/934/935/936 uses an enhanced 80C51 CPU which runs at six times the speed of standard 80C51 devices. A machine cycle consists of two CPU clock cycles, and most instructions execute in one or two machine cycles.

8.3 Clocks

8.3.1 Clock definitions

The P89LPC933/934/935/936 device has several internal clocks as defined below:

OSCCLK — Input to the DIVM clock divider. OSCCLK is selected from one of four clock sources (see Figure 8) and can also be optionally divided to a slower frequency (see Section 8.8 “CCLK modification: DIVM register”).

Remark: f_{osc} is defined as the OSCCLK frequency.

CCLK — CPU clock; output of the clock divider. There are two CCLK cycles per machine cycle, and most instructions are executed in one to two machine cycles (two or four CCLK cycles).

RCCLK — The internal 7.373 MHz RC oscillator output.

PCLK — Clock for the various peripheral devices and is $^{CCLK}/_{2}$.

8.3.2 CPU clock (OSCCLK)

The P89LPC933/934/935/936 provides several user-selectable oscillator options in generating the CPU clock. This allows optimization for a range of needs from high precision to lowest possible cost. These options are configured when the flash is programmed and include an on-chip watchdog oscillator, an on-chip RC oscillator, an oscillator using an external crystal, or an external clock source. The crystal oscillator can be optimized for low, medium, or high frequency crystals covering a range from 20 kHz to 18 MHz.

8.3.3 Low speed oscillator option

This option supports an external crystal in the range of 20 kHz to 100 kHz. Ceramic resonators are also supported in this configuration.

8.3.4 Medium speed oscillator option

This option supports an external crystal in the range of 100 kHz to 4 MHz. Ceramic resonators are also supported in this configuration.

8.3.5 High speed oscillator option

This option supports an external crystal in the range of 4 MHz to 18 MHz. Ceramic resonators are also supported in this configuration.

8.3.6 Clock output

The P89LPC933/934/935/936 supports a user-selectable clock output function on the XTAL2/CLKOUT pin when crystal oscillator is not being used. This condition occurs if another clock source has been selected (on-chip RC oscillator, watchdog oscillator,

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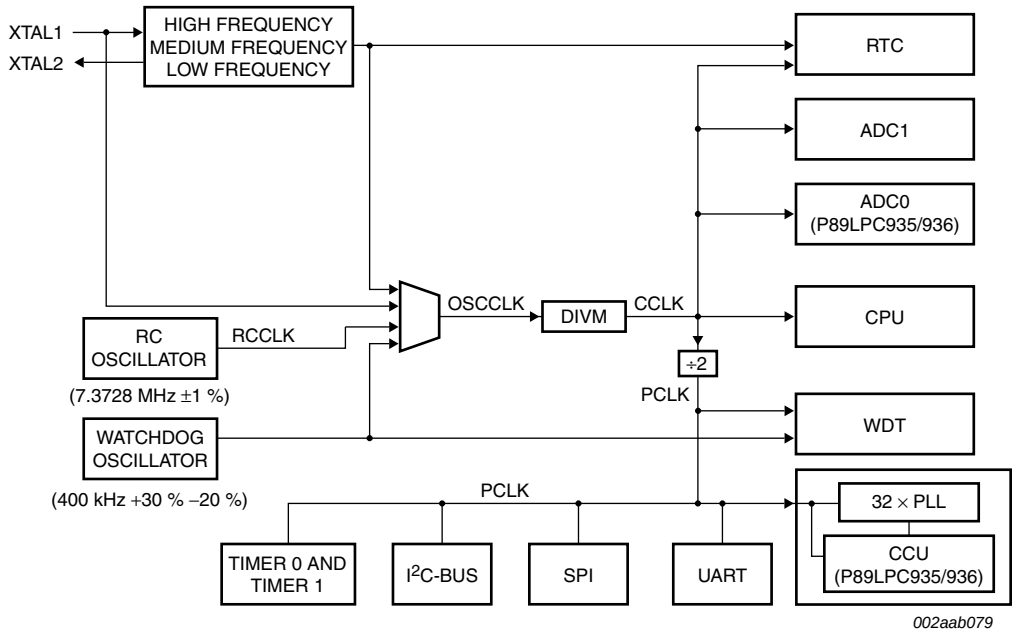

Fig 8. Block diagram of oscillator control

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- CODE

  64 kB of code memory space, accessed as part of program execution and via the MOVC instruction. The P89LPC933/934/935/936 have 4 KB/8 kB/16 kB of on-chip Code memory.

The P89LPC935/936 also has 512 bytes of on-chip data EEPROM that is accessed via SFRs (see Section 8.27 “Data EEPROM (P89LPC935/936)”).

8.11 Data RAM arrangement

The 768 bytes of on-chip RAM are organized as shown in Table 7.

Table 7. On-chip data memory usages

Type	Data RAM	Size (bytes)
DATA	Memory that can be addressed directly and indirectly	128
IDATA	Memory that can be addressed indirectly	256
XDATA	Auxiliary (‘External Data’) on-chip memory that is accessed using the MOVX instructions (P89LPC935/936)	512

8.12 Interrupts

The P89LPC933/934/935/936 uses a four priority level interrupt structure. This allows great flexibility in controlling the handling of the many interrupt sources. The P89LPC933/934/935/936 supports 15 interrupt sources: external interrupts 0 and 1, timers 0 and 1, serial port Tx, serial port Rx, combined serial port Rx/Tx, brownout detect, watchdog/Real-Time clock, I^2C-bus, keyboard, comparators 1 and 2, SPI, CCU, data EEPROM write/ADC completion.

Each interrupt source can be individually enabled or disabled by setting or clearing a bit in the interrupt enable registers IEN0 or IEN1. The IEN0 register also contains a global disable bit, EA, which disables all interrupts.

Each interrupt source can be individually programmed to one of four priority levels by setting or clearing bits in the interrupt priority registers IP0, IP0H, IP1, and IP1H. An interrupt service routine in progress can be interrupted by a higher priority interrupt, but not by another interrupt of the same or lower priority. The highest priority interrupt service cannot be interrupted by any other interrupt source. If two requests of different priority levels are pending at the start of an instruction, the request of higher priority level is serviced.

If requests of the same priority level are pending at the start of an instruction, an internal polling sequence determines which request is serviced. This is called the arbitration ranking.

Remark: The arbitration ranking is only used to resolve pending requests of the same priority level.

8.12.1 External interrupt inputs

The P89LPC933/934/935/936 has two external interrupt inputs as well as the Keypad Interrupt function. The two interrupt inputs are identical to those present on the standard 80C51 microcontrollers.

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8.13 I/O ports

The P89LPC933/934/935/936 has four I/O ports: Port 0, Port 1, Port 2, and Port 3. Ports 0, 1 and 2 are 8-bit ports, and Port 3 is a 2-bit port. The exact number of I/O pins available depends upon the clock and reset options chosen, as shown in Table 8.

Table 8. Number of I/O pins available

Clock source	Reset option	Number of I/O pins (28-pin package)
On-chip oscillator or watchdog oscillator	No external reset (except during power-up)	26
	External $\overline{\text{RST}}$ pin supported	25
External clock input	No external reset (except during power-up)	25
	External $\overline{\text{RST}}$ pin supported[1]	24
Low/medium/high speed oscillator (external crystal or resonator)	No external reset (except during power-up)	24
	External $\overline{\text{RST}}$ pin supported[1]	23

[1] Required for operation above 12 MHz.

8.13.1 Port configurations

All but three I/O port pins on the P89LPC933/934/935/936 may be configured by software to one of four types on a bit-by-bit basis. These are: quasi-bidirectional (standard 80C51 port outputs), push-pull, open drain, and input-only. Two configuration registers for each port select the output type for each port pin.

1. P1.5 ($\overline{\text{RST}}$) can only be an input and cannot be configured.
2. P1.2 (SCL/T0) and P1.3 (SDA/$\overline{\text{INT0}}$) may only be configured to be either input-only or open-drain.

8.13.1.1 Quasi-bidirectional output configuration

Quasi-bidirectional output type can be used as both an input and output without the need to reconfigure the port. This is possible because when the port outputs a logic HIGH, it is weakly driven, allowing an external device to pull the pin LOW. When the pin is driven LOW, it is driven strongly and able to sink a fairly large current. These features are somewhat similar to an open-drain output except that there are three pull-up transistors in the quasi-bidirectional output that serve different purposes.

The P89LPC933/934/935/936 is a 3 V device, but the pins are 5 V-tolerant. In quasi-bidirectional mode, if a user applies 5 V on the pin, there will be a current flowing from the pin to V_{DD}, causing extra power consumption. Therefore, applying 5 V in quasi-bidirectional mode is discouraged.

A quasi-bidirectional port pin has a Schmitt trigger input that also has a glitch suppression circuit.

8.13.1.2 Open-drain output configuration

The open-drain output configuration turns off all pull-ups and only drives the pull-down transistor of the port driver when the port latch contains a logic 0. To be used as a logic output, a port configured in this manner must have an external pull-up, typically a resistor tied to V_{DD}.

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Capture Noise Filter bit. If set, the capture logic needs to see four consecutive samples of the same value in order to recognize an edge as a capture event. An event counter can be set to delay a capture by a number of capture events.

8.19.6 PWM operation

PWM operation has two main modes, symmetrical and asymmetrical.

In asymmetrical PWM operation the CCU timer operates in down-counting mode regardless of the direction control bit.

In symmetrical mode, the timer counts up/down alternately. The main difference from basic timer operation is the operation of the compare module, which in PWM mode is used for PWM waveform generation.

As with basic timer operation, when the PWM (compare) pins are connected to the compare logic, their logic state remains unchanged. However, since bit FCO is used to hold the halt value, only a compare event can change the state of the pin.

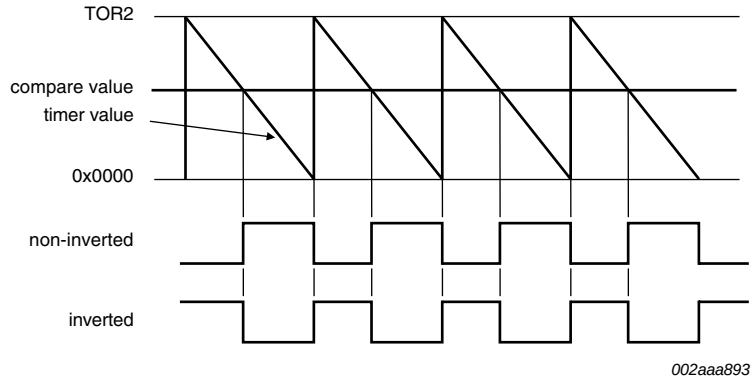

Fig 10. Asymmetrical PWM, down-counting mode

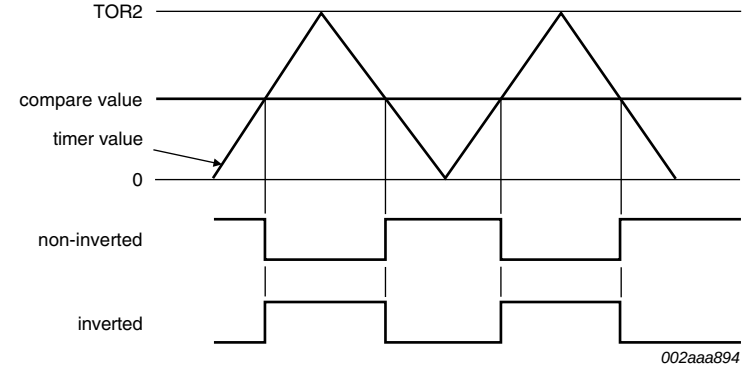

Fig 11. Symmetrical PWM

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8.19.9 CCU interrupts

There are seven interrupt sources on the CCU which share a common interrupt vector.

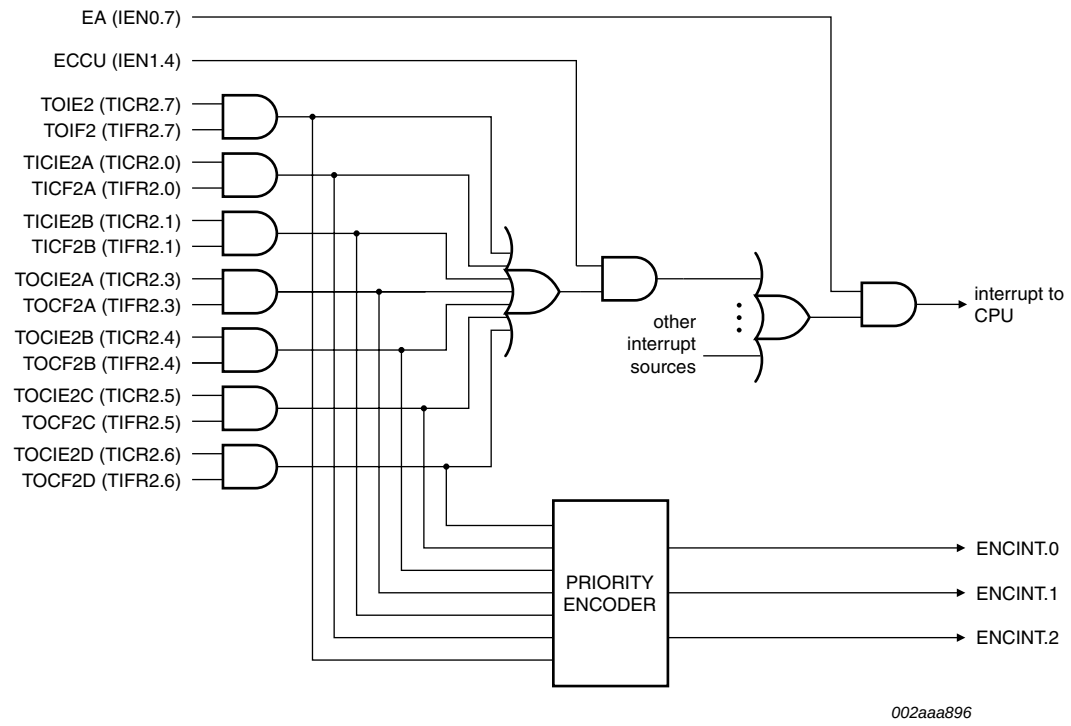

Fig 13. Capture/compare unit interrupts

8.20 UART

The P89LPC933/934/935/936 has an enhanced UART that is compatible with the conventional 80C51 UART except that Timer 2 overflow cannot be used as a baud rate source. The P89LPC933/934/935/936 does include an independent baud rate generator. The baud rate can be selected from the oscillator (divided by a constant), Timer 1 overflow, or the independent baud rate generator. In addition to the baud rate generation, enhancements over the standard 80C51 UART include Framing Error detection, automatic address recognition, selectable double buffering and several interrupt options. The UART can be operated in four modes: shift register, 8-bit UART, 9-bit UART, and CPU $^{clock}/_{32}$ or CPU $^{clock}/_{16}$.

8.20.1 Mode 0

Serial data enters and exits through RXD. TXD outputs the shift clock. 8 bits are transmitted or received, LSB first. The baud rate is fixed at $^{1}/_{16}$ of the CPU clock frequency.

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8.22.1 Typical SPI configurations

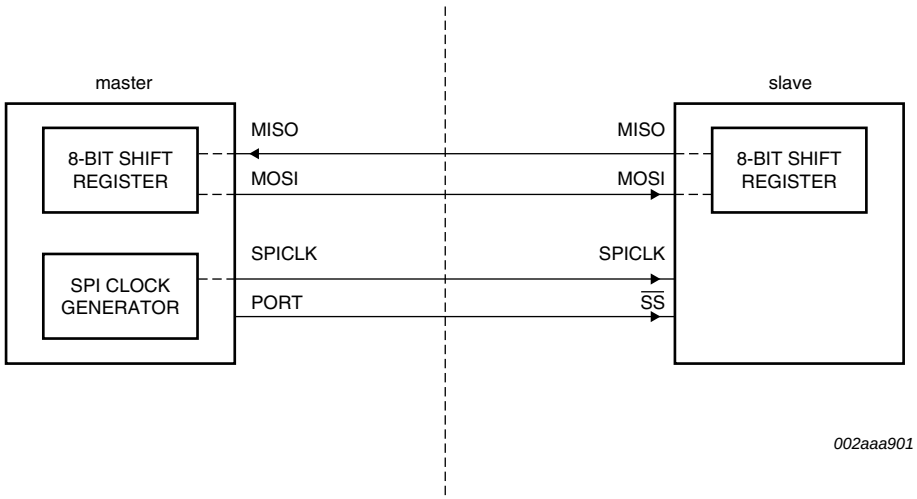

Fig 18. SPI single master single slave configuration

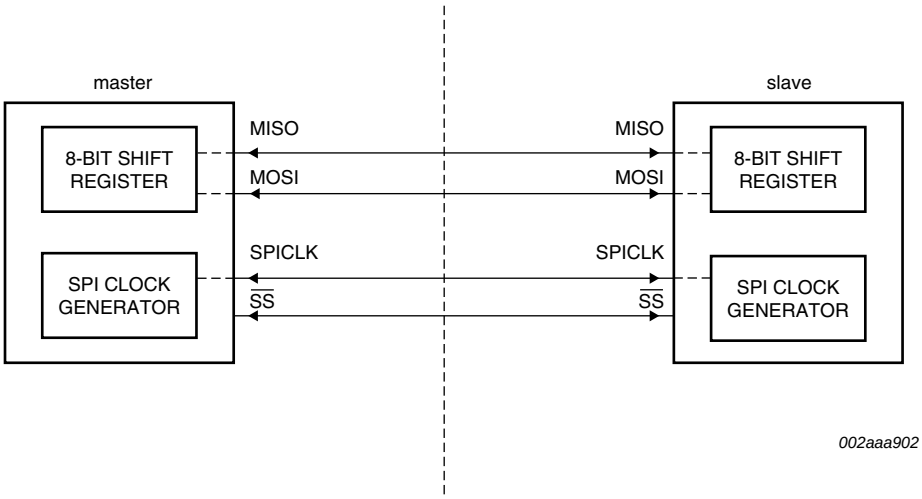

Fig 19. SPI dual device configuration, where either can be a master or a slave

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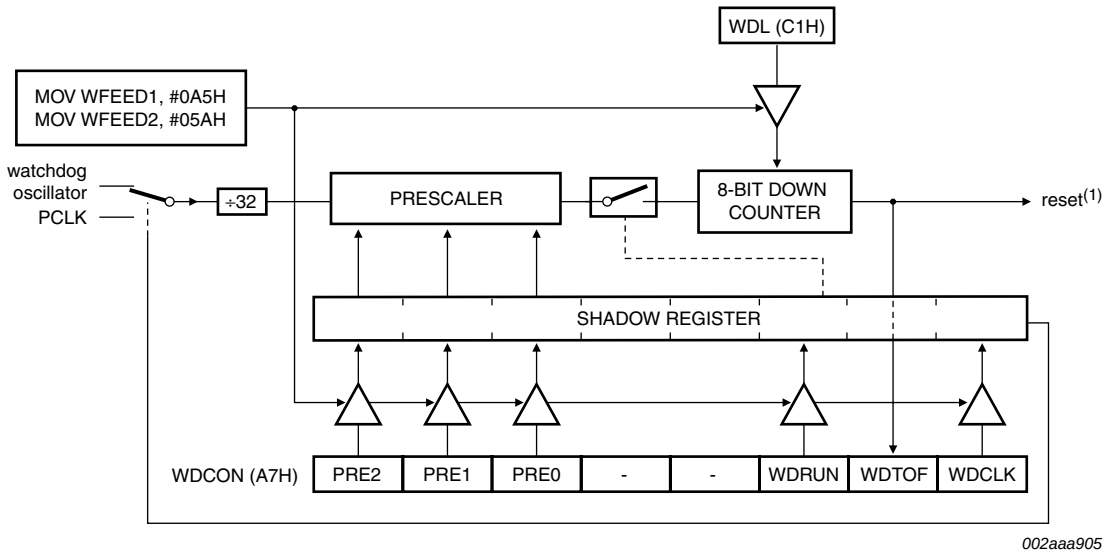
8.25 Watchdog timer

The watchdog timer causes a system reset when it underflows as a result of a failure to feed the timer prior to the timer reaching its terminal count. It consists of a programmable 12-bit prescaler, and an 8-bit down counter. The down counter is decremented by a tap taken from the prescaler. The clock source for the prescaler is either the PCLK or the nominal 400 kHz watchdog oscillator. The watchdog timer can only be reset by a power-on reset. When the watchdog feature is disabled, it can be used as an interval timer and may generate an interrupt. Figure 22 shows the watchdog timer in Watchdog mode. Feeding the watchdog requires a two-byte sequence. If PCLK is selected as the watchdog clock and the CPU is powered-down, the watchdog is disabled. The watchdog timer has a time-out period that ranges from a few μs to a few seconds. Please refer to the P89LPC933/934/935/936 *User manual* for more details.



(1) Watchdog reset can also be caused by an invalid feed sequence, or by writing to WDCON not immediately followed by a feed sequence.

Fig 22. Watchdog timer in Watchdog mode (WDTE = 1)

8.26 Additional features

8.26.1 Software reset

The SRST bit in AUXR1 gives software the opportunity to reset the processor completely, as if an external reset or watchdog reset had occurred. Care should be taken when writing to AUXR1 to avoid accidental software resets.

8.26.2 Dual data pointers

The dual Data Pointers (DPTR) provides two different Data Pointers to specify the address used with certain instructions. The DPS bit in the AUXR1 register selects one of the two Data Pointers. Bit 2 of AUXR1 is permanently wired as a logic 0 so that the DPS bit may be toggled (thereby switching Data Pointers) simply by incrementing the AUXR1 register, without the possibility of inadvertently altering other bits in the register.

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Table 13. Dynamic characteristics (18 MHz) *…continued*

V_{DD} = 3.0 V to 3.6 V unless otherwise specified.

T_{amb} = −40 °C to +85 °C for industrial, −40 °C to +125 °C for extended, unless otherwise specified.[1][2]

Symbol	Parameter	Conditions	Variable clock		f_{osc} = 18 MHz		Unit
			Min	Max	Min	Max	
$t_{SPICLKH}$	SPICLK HIGH time	see Figure 26, 28, 29, 30					
	master		$^{2}/_{CCLK}$	-	111	-	ns
	slave		$^{3}/_{CCLK}$	-	167	-	ns
$t_{SPICLKL}$	SPICLK LOW time	see Figure 26, 28, 29, 30					
	master		$^{2}/_{CCLK}$	-	111	-	ns
	slave		$^{3}/_{CCLK}$	-	167	-	ns
t_{SPIDSU}	SPI data set-up time	see Figure 26, 28, 29, 30					
	master or slave		100	-	100	-	ns
t_{SPIDH}	SPI data hold time	see Figure 26, 28, 29, 30					
	master or slave		100	-	100	-	ns
t_{SPIA}	SPI access time	see Figure 29, 30					
	slave		0	80	0	80	ns
t_{SPIDIS}	SPI disable time	see Figure 29, 30					
	slave		0	160	-	160	ns
t_{SPIDV}	SPI enable to output data valid time	see Figure 26, 28, 29, 30					
	slave		-	160	-	160	ns
	master		-	111	-	111	ns
t_{SPIOH}	SPI output data hold time	see Figure 26, 28, 29, 30	0	-	0	-	ns
t_{SPIR}	SPI rise time	see Figure 26, 28, 29, 30					
	SPI outputs (SPICLK, MOSI, MISO)		-	100	-	100	ns
	SPI inputs (SPICLK, MOSI, MISO, $\overline{SS}$)		-	2000	-	2000	ns
t_{SPIF}	SPI fall time	see Figure 26, 28, 29, 30					
	SPI outputs (SPICLK, MOSI, MISO)		-	100	-	100	ns
	SPI inputs (SPICLK, MOSI, MISO, $\overline{SS}$)		-	2000	-	2000	ns

[1] Parameters are valid over ambient temperature range unless otherwise specified.

[2] Parts are tested to 2 MHz, but are guaranteed to operate down to 0 Hz.

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13.2 ADC electrical characteristics

Table 16. ADC electrical characteristics

V_{DD} = 2.4 V to 3.6 V, unless otherwise specified.
T_{amb} = −40 °C to +85 °C for industrial, −40 °C to +125 °C for extended, unless otherwise specified.
All limits valid for an external source impedance of less than 10 kΩ.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{IA}	analog input voltage		V_{SS} −0.2	-	V_{DD} +0.2	V
C_{iss}	input capacitance		-	-	15	pF
E_D	differential linearity error		-	-	±1	LSB
$E_{L(adj)}$	integral non-linearity		-	-	±1	LSB
E_O	offset error		-	-	±2	LSB
E_G	gain error		-	-	±1	%
$E_{u(tot)}$	total unadjusted error		-	-	±2	LSB
M_{CTC}	channel-to-channel matching		-	-	±1	LSB
$\alpha_{ct(port)}$	crosstalk between port inputs	0 kHz to 100 kHz	-	-	−60	dB
SR_{in}	input slew rate		-	-	100	V/ms
$T_{cy(ADC)}$	ADC clock cycle time		111	-	2000	ns
t_{ADC}	ADC conversion time	A/D enabled	-	-	$13T_{cy(ADC)}$	ns

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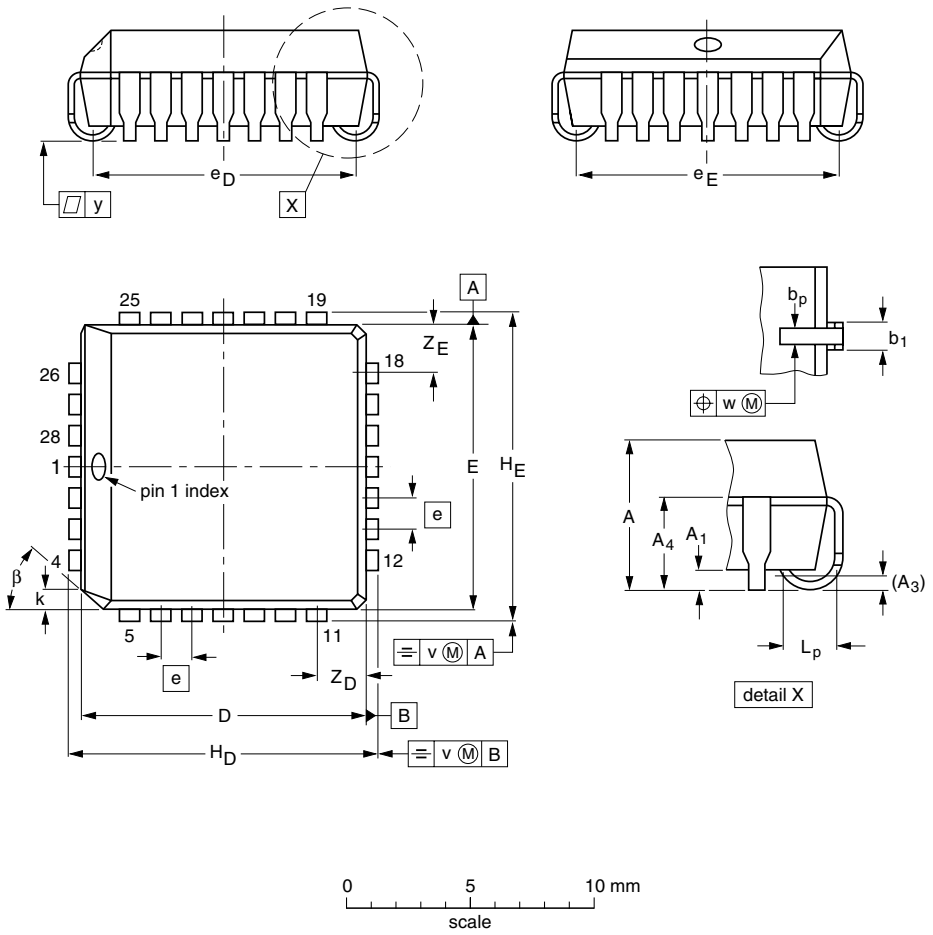
14. Package outline

PLCC28: plastic leaded chip carrier; 28 leads **SOT261-2**



DIMENSIONS (mm dimensions are derived from the original inch dimensions)

UNIT	A	A_1 min.	A_3	A_4 max.	b_p	b_1	$D^{(1)}$	$E^{(1)}$	e	e_D	e_E	H_D	H_E	k	L_p	v	w	y	$Z_D^{(1)}$ max.	$Z_E^{(1)}$ max.	β
mm	4.57 4.19	0.51	0.25	3.05	0.53 0.33	0.81 0.66	11.58 11.43	11.58 11.43	1.27	10.92 9.91	10.92 9.91	12.57 12.32	12.57 12.32	1.22 1.07	1.44 1.02	0.18	0.18	0.1	2.16	2.16	45°
inches	0.180 0.165	0.02	0.01	0.12	0.021 0.013	0.032 0.026	0.456 0.450	0.456 0.450	0.05	0.43 0.39	0.43 0.39	0.495 0.485	0.495 0.485	0.048 0.042	0.057 0.040	0.007	0.007	0.004	0.085	0.085	

Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT261-2	112E08	MS-018	EDR-7319			~~99-12-27~~ 01-11-15

Fig 32. Package outline SOT261-2 (PLCC28)

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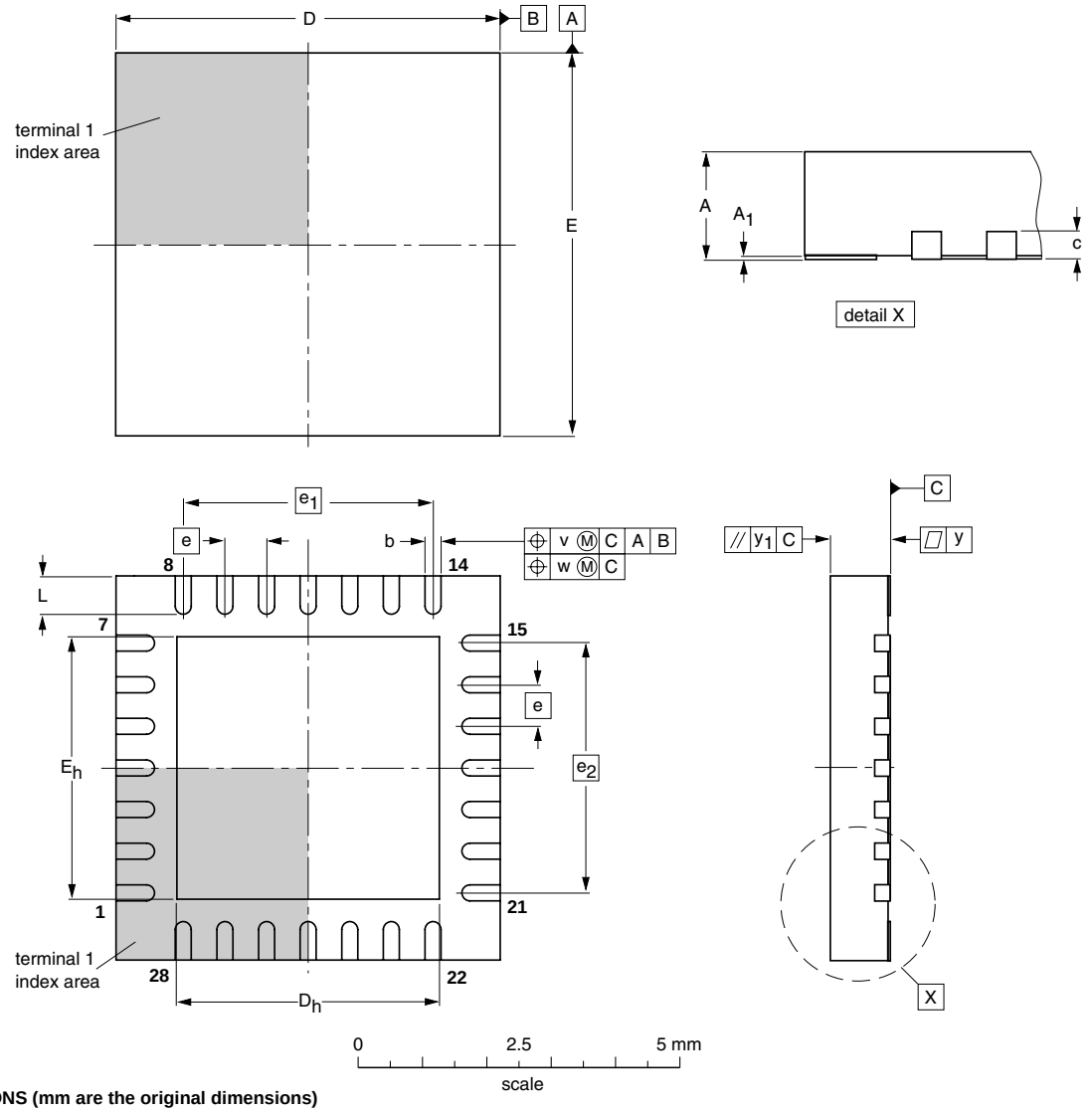
HVQFN28: plastic thermal enhanced very thin quad flat package; no leads; 28 terminals; body 6 x 6 x 0.85 mm **SOT788-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A(1) max.	A_1	b	c	D(1)	D_h	E(1)	E_h	e	e_1	e_2	L	v	w	y	y_1
mm	1	0.05 0.00	0.35 0.25	0.2	6.1 5.9	4.25 3.95	6.1 5.9	4.25 3.95	0.65	3.9	3.9	0.75 0.50	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT788-1	- - -	MO-220	- - -			02-10-22

Fig 34. Package outline SOT788-1 (HVQFN28)

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15. Abbreviations

Table 17. Acronym list

Acronym	Description
A/D	Analog to Digital
CPU	Central Processing Unit
DAC	Digital to Analog Converter
EPROM	Erasable Programmable Read-Only Memory
EEPROM	Electrically Erasable Programmable Read-Only Memory
EMI	Electro-Magnetic Interference
LED	Light Emitting Diode
PWM	Pulse Width Modulator
RAM	Random Access Memory
RC	Resistance-Capacitance
RTC	Real-Time Clock
SAR	Successive Approximation Register
SFR	Special Function Register
SPI	Serial Peripheral Interface
UART	Universal Asynchronous Receiver/Transmitter

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16. Revision history

Table 18. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
P89LPC933_934_ 935_936 v.8	20110112	Product data sheet	-	P89LPC933_934_ 935_936 v.7
Modifications:	• Table 10 “Limiting values”: Changed V_n max to 5.5 V. • Table 11 “Static characteristics”: Added V_{POR}. • Table 16 “ADC electrical characteristics”: Corrected V_{IA} max. • Section 8.16 “Reset”: Added sentence “When this pin functions as a reset input....”			
P89LPC933_934_ 935_936 v.7	20081126	Product data sheet	-	P89LPC933_934_ 935_936 v.6
P89LPC933_934_ 935_936 v.6	20050620	Product data sheet	-	P89LPC933_934_ 935_936 v.5
P89LPC933_934_ 935_936 v.5	20041103	Product data sheet	-	P89LPC933_934_ 935 v.4
P89LPC933_934_ 935 v.4	20040209	Objective data	-	P89LPC933_934_ 935 v.3

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17. Legal information

17.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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